

PCN #: 08_0085

Title:

AD5522 Device iteration to improve FI ac crosstalk

Date Published:

September 19, 2008

Type:

Device

Part Number:

AD5522

Proposed Change:

From: Wafer Fabrication Manufacturing part number YJ40B (S4 silicon)

To: Wafer Fabrication Manufacturing part number YJ40C (S5 silicon)

Metal iteration on AD5522 die.

Wafer fabrication process, die size and data sheet specifications remain unchanged.

In addition to this iteration the following unrelated data sheet changes have been made.

Datasheet specification changes unrelated to design change

- Measure Current Common-Mode Error from +/-0.01% to +/-0.005% (gain = 5)
- Timing SPI T16 correction to units from ns to us (micro)
- LVDS Timing
- change to specs to target 100MHz SCLK frequency (DVCC = 4.5V to 5.25V).
- Leakage current of CPOH1/SDOb and SDO changes from +/-1uA to +/-2uA.

Addition of new specs unrelated to design change

- Combined leakage at DUT (25degC to 70degC) +/-15nA.

Reason for Change:

The purpose of this metal iteration is to improve FI ac crosstalk (Fig. 25 on AD5522 datasheet Rev.0). There is no further change in the function and performance of the AD5522.

Summary of Supporting Information:

Qualification results are contained in the attached report

Material shipped with an assembly date-code of 0831, or with an assembly date-code of 0839 onwards, will have S5 silicon.

Planned Date Change Effective:

October 1, 2008

EIA Date Code:

0840

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